

H5N2519P

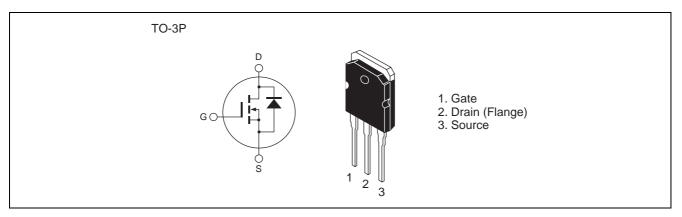
Silicon N Channel MOS FET High Speed Power Switching

> REJ03G0478-0200 Rev.2.00 Nov.19.2004

Features

- Low on-resistance
- Low leakage current
- High speed switching

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit	
Drain to Source voltage	V _{DSS}	250	V	
Gate to Source voltage	V _{GSS}	±30	V	
Drain current	ID	65	A	
Drain peak current	Note1 I _{D (pulse)}	195	A	
Body-Drain diode reverse Drain current	I _{DR}	65	A	
Avalanche current	I _{AP} ^{Note3}	22	A	
Avalanche energy	E _{AR} ^{Note3}	30.2	mJ	
Channel dissipation	Pch Note2	150	W	
Channel to case thermal impedance	θch-c	0.833	°C/W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Notes: 1. $PW \le 10 \ \mu s$, duty cycle $\le 1\%$

2. Value at Tc = 25° C

3. STch = 25° C, Tch $\leq 150^{\circ}$ C

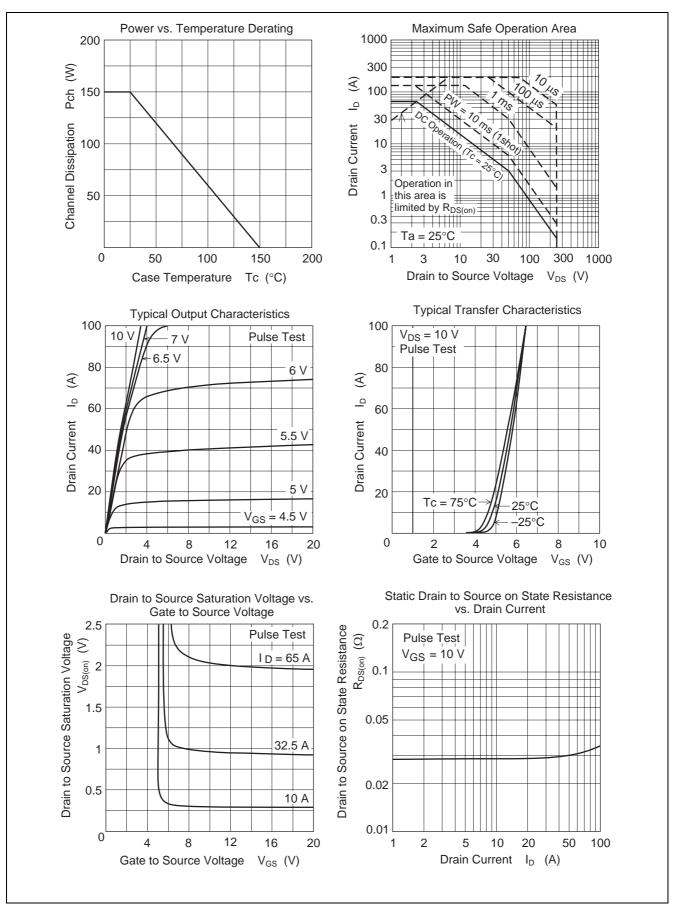
Electrical Characteristics

Symbol	Min	Тур	Max	Unit	Test conditions
V _{(BR)DSS}	250		—	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
I _{DSS}	_	—	1	μΑ	$V_{DS} = 250 \text{ V}, V_{GS} = 0$
I _{GSS}	_		±0.1	μΑ	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0$
V _{GS(off)}	3.0	_	4.5	V	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$
yfs	28	47	—	S	$I_D = 32.5 \text{ A}, V_{DS} = 10 \text{ V}^{Note4}$
R _{DS(on)}	_	0.029	0.035	Ω	$I_D = 32.5 \text{ A}, V_{GS} = 10 \text{ V}^{Note4}$
Ciss	—	4900	—	pF	V _{DS} = 25 V V _{GS} = 0 f = 1 MHz
Coss	—	700	—	pF	
Crss	_	75	—	pF	
td(on)	_	65	—	ns	$I_D = 32.5 \text{ A}$ $V_{GS} = 10 \text{ V}$ $R_L = 3.9 \Omega$ $Rg = 10 \Omega$
tr	_	310	—	ns	
td(off)	_	220	_	ns	
tf		220		ns	
Qg		120		nC	$V_{DD} = 200 V$ $V_{GS} = 10 V$ $I_D = 65 A$
Qgs		28		nC	
Qgd		52		nC	
V_{DF}	_	1.10	1.65	V	$I_F = 65 \text{ A}, V_{GS} = 0^{Note4}$
trr	_	200	_	ns	$I_F = 65 \text{ A}, V_{GS} = 0$ diF/dt = 100 A/ μ s
Qrr	_	1.6	_	μC	
	V _{(BR)DSS} I _{DSS} I _{GSS} V _{GS(off)} yfs R _{DS(on)} Ciss Coss Crss Crss td(on) tr td(off) tf Qg Qgs Qgs Qgd V _{DF} trr	V(BR)DSS 250 IDSS IGSS VGS(off) 3.0 Iyfs 28 RDS(on) Ciss Coss Crss td(on) tf Qg Qgs Vdoff Tf Qg Qgd Tr	V(BR)DSS 250 IDSS IGSS IGSS VGS(off) 3.0 Iyfs 28 47 RDS(on) 0.029 Ciss 4900 Coss 700 Crss 75 td(on) 65 tr 310 td(off) 220 Qg 120 Qgs 28 Qgd 52 VDF 200	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	$\begin{array}{c c c c c c c c c c c c c c c c c c c $

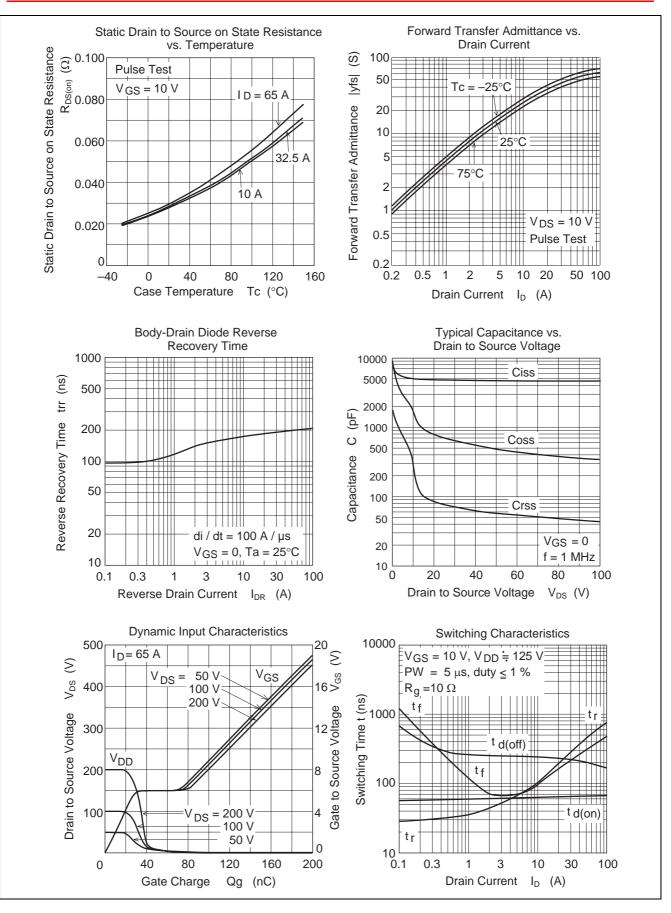
Notes: 4. Pulse test



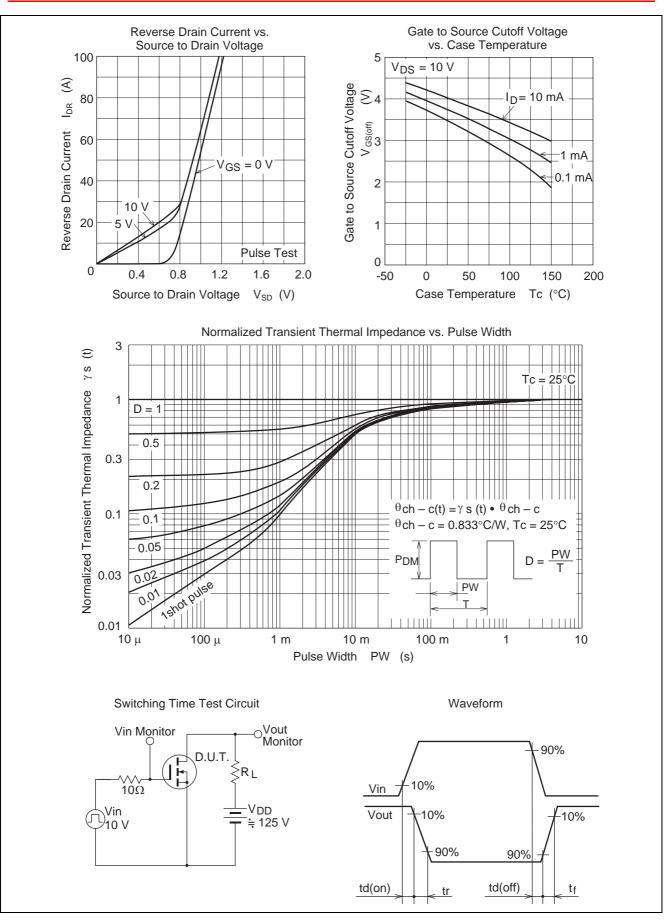
Main Characteristics



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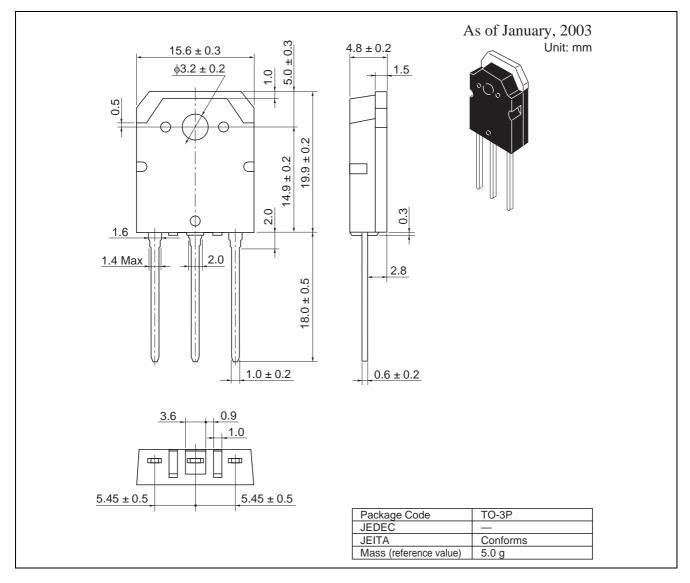








Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
H5N2519P-E	30 pcs	Plastic magazine

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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